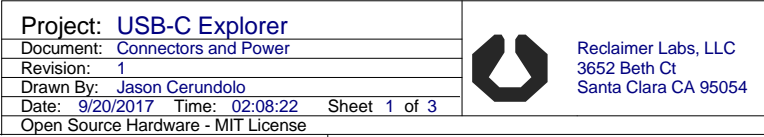
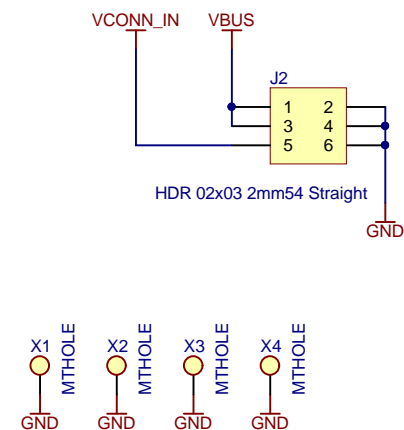
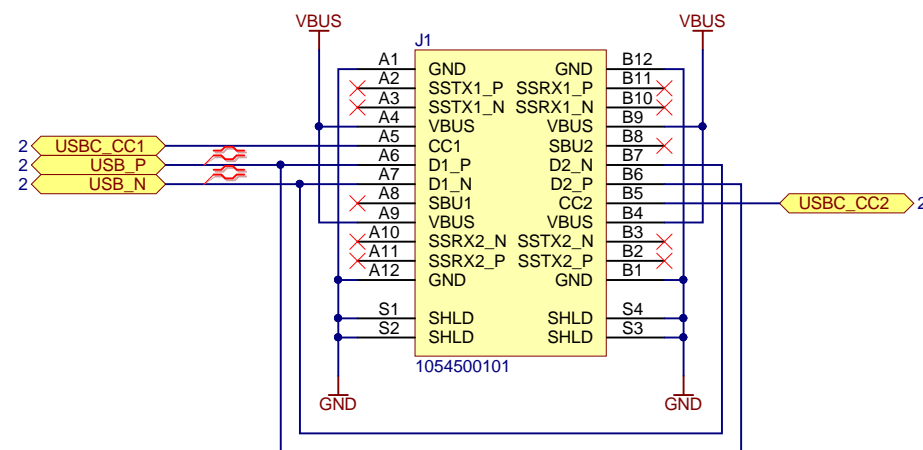
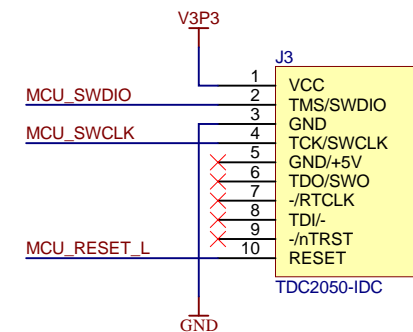
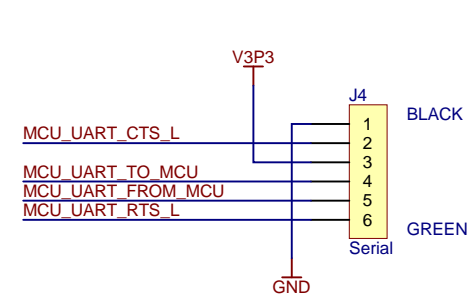
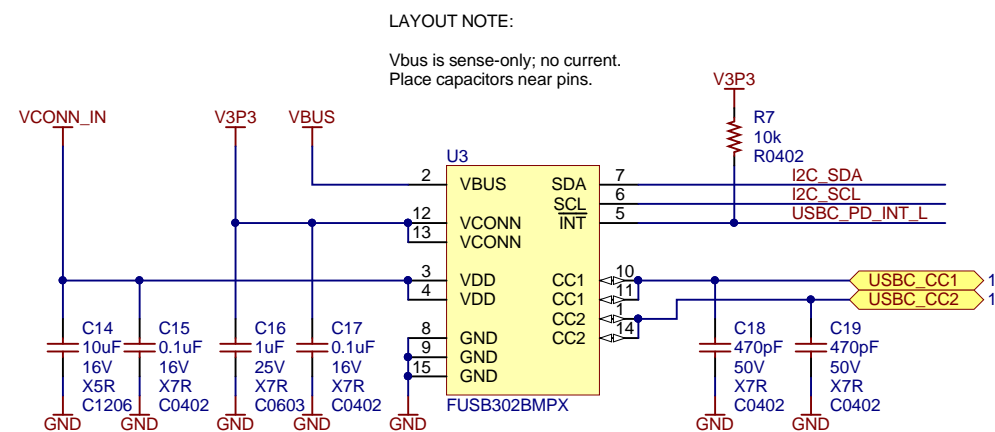
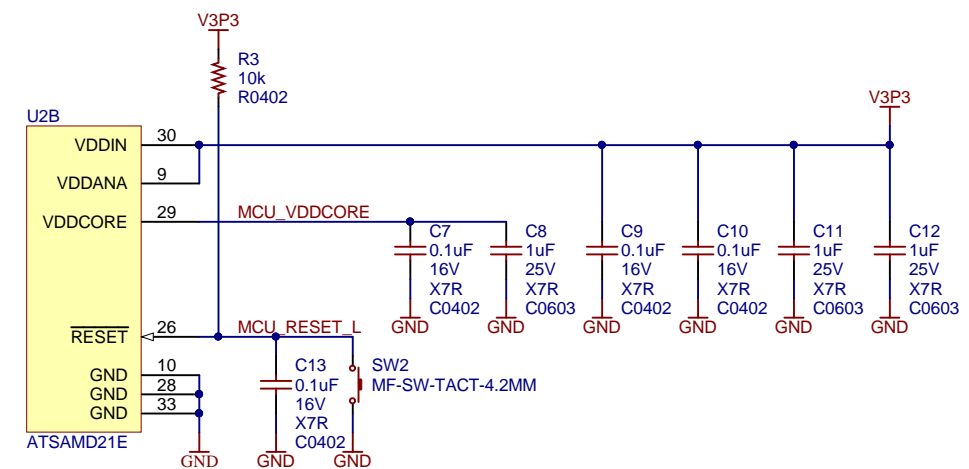
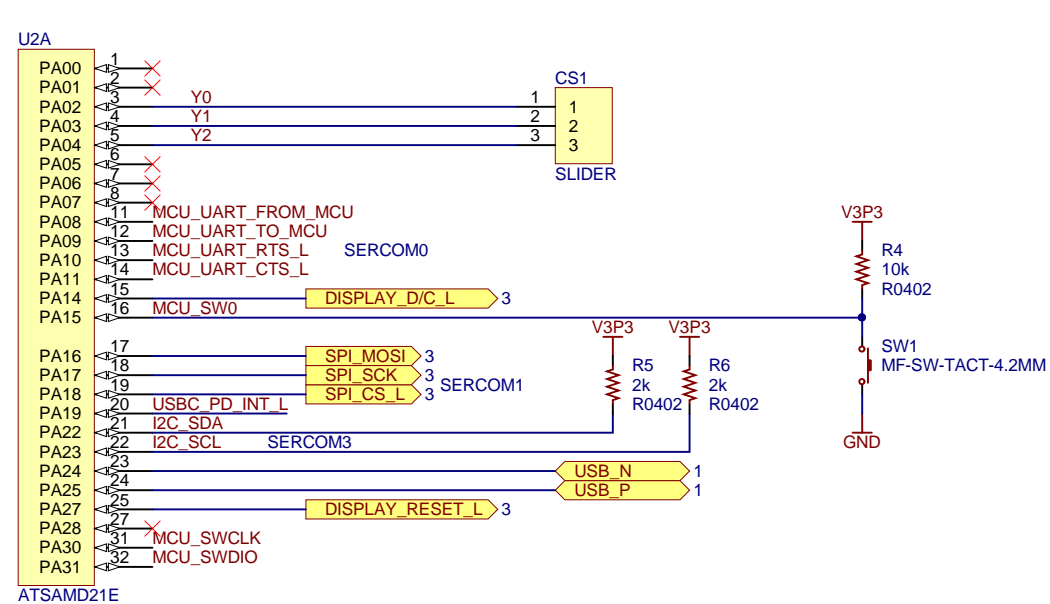


The block diagram illustrates the internal architecture of the USB-C module. A central USB-C port is connected to the FUSB302B chip via a bidirectional BMC (Bus Master Control) interface. The FUSB302B chip is connected to the SAMD21E microcontroller via an I2C interface. The SAMD21E microcontroller is connected to the USB-C port via a bidirectional USB interface. Additionally, the SAMD21E microcontroller is connected to a Debug/JTAG Conn via a bidirectional SWD (Serial Wire Debug) interface. The SAMD21E microcontroller is also connected to an OLED Display via an SPI (Serial Peripheral Interface) interface. The Power Conn is connected to the USB-C port and the FUSB302B chip.

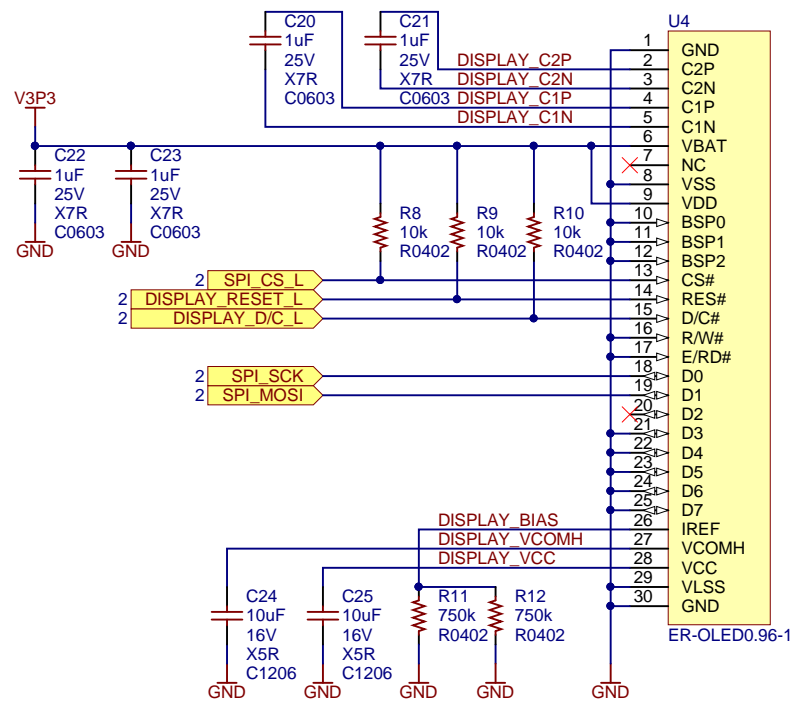




LAYOUT NOTE:

Vbus is sense-only; no current.
Place capacitors near pins.





BSP[2..0] = 0 => 4-wire SPI

Section 8.1.3 of the SSD1306
datasheet calls for D3 thru D7,
E/RD#, R/W# can be tied to GND.
D2 should be left floating.

I_REF is recommended to be 12.5 +/- 2 uA.
V_IREF = VCC - 2.5
When using internal boost, VCC = 7.25V.
Two 750k resistors are used to match
MacroFab House Parts and save cost.